



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



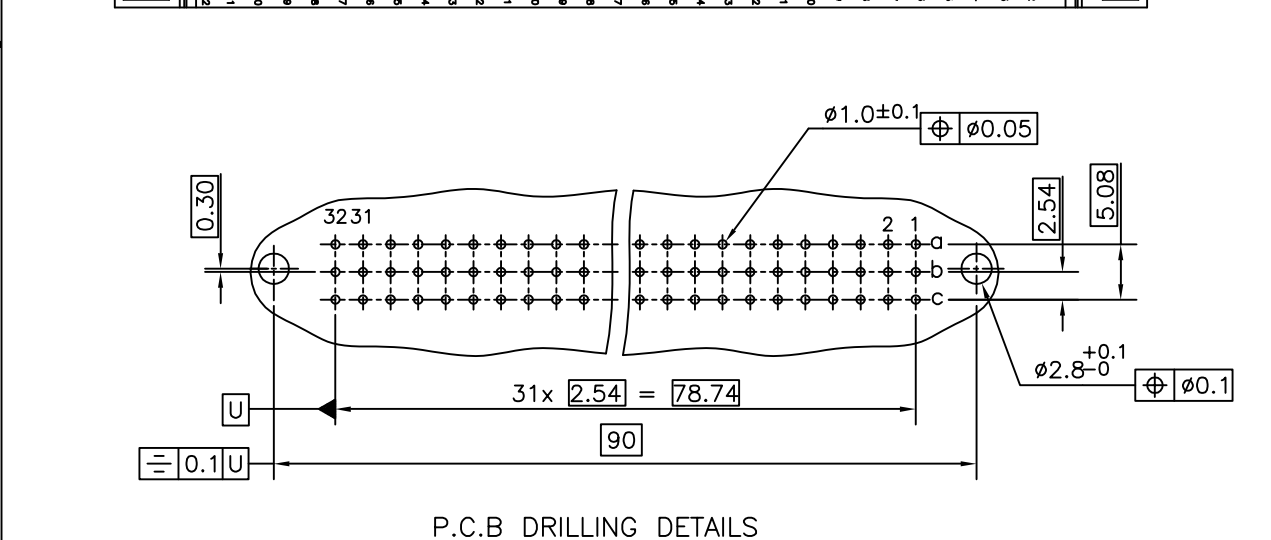
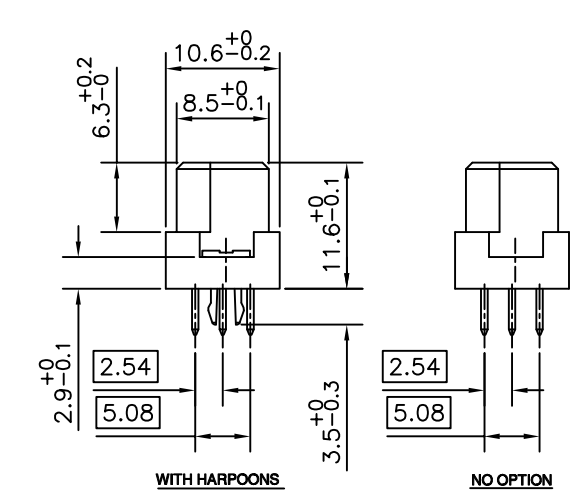
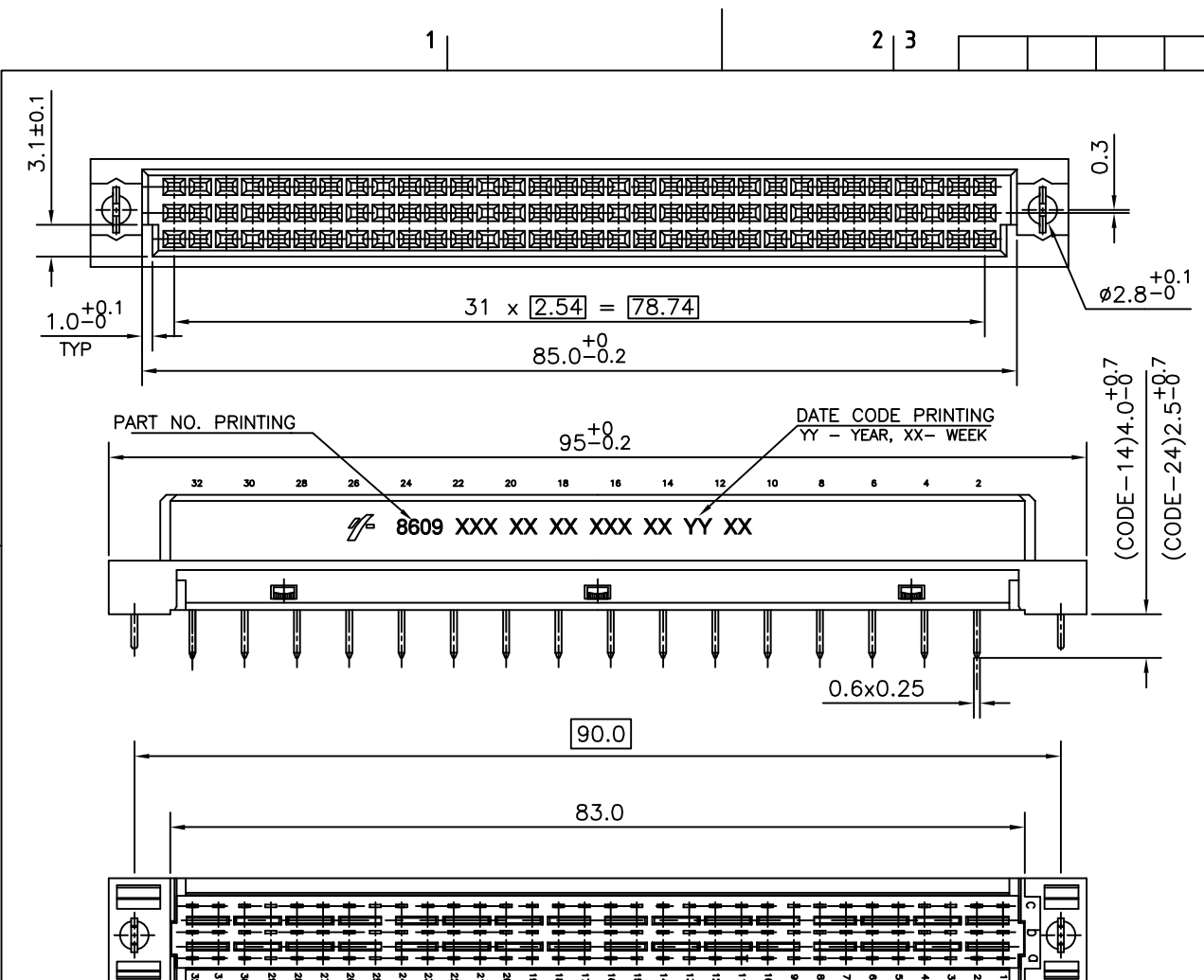
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NOTES:-

1. THE "LF" PRODUCTS MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
2. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 3.5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6 MM MINIMUM THICK CIRCUIT BOARD
3. LEAD FREE OR RoHS DIRECTIVE LABELING TO BE PROVIDED AS PER GS-14-920 FOR LEAD FREE VERSION.

TECHNICAL SPECIFICATION

HOUSING MATERIAL : POLYESTER THERMOPLASTIC UL94V-0, GREY
HOUSING CAN WITHSTAND EXPOSURE TO LEAD FREE WAVE SOLDERING TEMPERATURE OF 260-265°C FOR STRAIGHT CONNECTORS AS IT IS IN CLASSICAL LEAD WAVE SOLDERING AT 235-250°C

CONTACT / HARPOON MATERIAL : COPPER ALLOY

CONTACT PLATING ACTIVE ZONE : GOLD OVER NICKEL

TERMINATION ZONE

TIN LEAD VERSION : TIN LEAD OVER NICKEL

LEAD FREE VERSION : TIN (PURE MATTE) OVER NI

HARPOON PLATING

TIN LEAD VERSION : TIN LEAD OVER NICKEL

LEAD FREE VERSION : TIN (PURE MATTE) OVER NI

ELECTRICAL DATA

CURRENT RATING AT 20°C : 1.5 A

CURRENT (I MAX) : 2 A

TEMPERATURE RANGE : -55°C/+125°C

CONTACT RESISTANCE : ≤ 20mΩ

INSULATION RESISTANCE : ≥ 10⁶MΩ

TEST VOLTAGE (rms) : 1000V

MECHANICAL DATA

INSERTION FORCE PER CONTACT : ≤ 0.94N

EXTRACTION FORCE PER CONTACT : ≥ 0.15N

REFERENCE SPECIFICATIONS : DIN 41612 / IEC 603-2

SERIES	8609	3	48	8	1	14	7	5	8	V1
ROWS FITTED WITH CONTACTS										
Rows a-b-c	3		48							
Rows a-c	4		32							
NUMBER OF CONTACTS										
TYPE OF INSULATOR										
3 ROW FEMALE INSULATOR	8									
METHOD OF MOUNTING										
STANDARD MOUNTING - STYLE C	1									
TERMINATION										
STRAIGHT SPILL (LONG)	14									
STRAIGHT SPILL (SHORT)	24									
OPTIONS										
NO OPTION	7									
WITH HARPOONS	H									
PERFORMANCE CLASS										
4 - DIN 41612 CLASS 3	4									
5 - DIN 41612 CLASS 2	5									
6 - DIN 41612 CLASS 1	6									
8 - AS PER MIL C 55302/JSS 50808	8									
PITCH PER ROW	5.08									
SPECIAL CODE										
V1	TIN LEAD VERSION									
V1LF	LEAD FREE VERSION									

mat'l. code		surface		tolerance		projection		product family	
-		ISO 1302		ISO 406 ISO 1101				8609	
litr		ecn no		dr		date		title	
A		I04-0100		MINI		09/11/2004		DIN STANDARD RECEPTACLE	
B		I05-0042		MINI		19/05/2005		STRAIGHT SPILL DIN 41612 STYLE-C	
C		I06-0063		MINI		01/06/2006			
				dr		MINI K VANDANATH 29/09/2004		dwg no	
				enfr		RAKHEE GEORGE 29/09/2004		sheet 1 of 1	
				chr		RAKHEE GEORGE 01/06/2006		size	
				appd		RAKHEE GEORGE 01/06/2006		A3	
sheet index		revision		C				type	
1		sheet		1				Product Customer Drawing	